

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 196273US-0 CONT		SERIAL NO. New Rule 1.53(b) Continuation Application	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Ende SHAN, et al.			
				FILING DATE HEREWITH		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
<i>SL</i>	AA	5,270,255	12/14/93	Wong			
<i>SL</i>	AB	5,108,951	04/28/92	Chen, et al.			
<i>SL</i>	AC	5,358,616	10/25/94	Ward			
<i>SL</i>	AD	5,600,182	02/04/97	Schinella, et al.			
<i>SL</i>	AE	5,693,564	12/22/94	Yu			
<i>SL</i>	AF	5,582,679	12/10/96	Liajun, et al.			
<i>SL</i>	AG	5,665,659	09/09/97	Lee, et al.			
<i>SL</i>	AH	5,158,933	10/27/92	Holtz, et al.			
<i>SL</i>	AI	4,970,176	11/13/90	Tracy, et al.			
<i>SL</i>	AJ	5,731,245	10/28/96	Joshi, et al.			
<i>SL</i>	AK	5,443,995	08/22/95	Nulman			
<i>SL</i>	AL	5,911,113	06/08/99	Yao, et al.			
<i>SL</i>	AM	5,374,592	12/20/94	MacNaughton, et al.			
<i>SL</i>	AN	5,371,042	12/06/94	Ong			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	AO						
	AP						
	AQ						
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	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
<i>SL</i>	AW	<u>Elsevier Science S.A.</u> , Thin Solid Films 253 (1994) 367-371, "A1 planarization processes for multilayer metallization of quarter micrometer devices", Zheng Xu,					
<i>SL</i>	AX	<u>Electronic Engineering Times (EETIMES)</u> , Issue 939, February 3, 1997, "A1 hits sub-0.25 micron vias", Title Page w. page 37 and page 42					
<i>SL</i>	AY	<u>Semiconductor International</u> , August 1994, "The Interconnect Challenge: Filling Small, High Aspect Ratio Contact Holes"					
<i>SL</i>	AZ	SPIE Vol. 2335, pp. 70-79, Invited Paper, Applied Material, Inc., PVD Division, Santa Clara, CA 95054, "Planar Multilevel Metallization Technologies for ULSI Devices", Zheng Xu,					
Examiner <i>Lamond T. Bledsoe</i>					Date Considered <i>1/24/2002</i>		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
<i>EW</i>	AAA	5,378,660	01/03/95	Ngan, et al.			
<i>EW</i>	AAB	5,108,570	04/28/92	Wang			
	AC						
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	AV						
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	AW						
	AX						
	AY						
	AZ						
Examiner <i>Lorenzo Toledo</i>					Date Considered <i>1/24/02</i>		
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